



Session Title:	[ThE2] Modeling Etch Processes
Session Date:	November 14 (Thu.), 2024
Session Time:	10:50-12:20
Session Room:	Room E (Sicily Room, 1F, Paradise Hotel Busan)
Session Chair:	Prof. Heeyeop Chae (Sungkyunkwan Univ., Korea)

[ThE2-1] [Invited] 10:50-11:20

Thermal Atomic Layer Etching Mechanism of Aluminum Oxide: A First Principle Study

Khabib Khumaini, Gyejun Cho, Hye-Lee Kim, and Won-Jun Lee (Sejong Univ., Korea)

[ThE2-2] 11:20-11:40

Ab Initio Investigation of Chelation on CoCl_2 Films for Atomic Layer Etching

Eugene Huh and Sangheon Lee (Ewha Womans Univ., Korea)

[ThE2-3] 11:40-12:00

Computational Study of Re-Deposition Effects due to Geometric Differences in MASK Patterns in High Aspect Ratio Plasma Etching

Byeong-Yeop Choi, Si-Jun Kim, Won-Nyoung Jeong, Young-Seok Lee, In-Ho Seong, Chul-Hee Cho, Min Su Choi, Seong-Hyun Seo, Woo-been Lee, and Shin-Jae You (Chungnam Nat'l Univ., Korea)

[ThE2-4] 12:00-12:20

A Unified Global Model Accompanied with a Voltage and Current Sensor for Low Pressure Capacitively Coupled RF Discharge

Inho Seong, Sijun Kim, Woobeen Lee, Youngseok Lee, Chulhee Cho, Wonnyoung Jeong, Minsu Choi, Byeongyeop Choi, Huichan Seo, Sangheon Song, and Shinjae You (Chungnam Nat'l Univ., Korea)